

## 900V N-ch Planar MOSFET

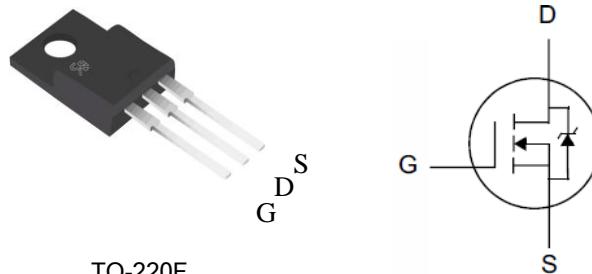
### General Features

- RoHS Compliant
- $R_{DS(ON),typ.}=1.4\ \Omega @ V_{GS}=10V$
- Low Gate Charge Minimize Switching Loss
- Fast Recovery Body Diode

$BV_{DSS}$	$R_{DS(ON),typ.}$	$I_D$
900V	1.4Ω	6.0A

### Applications

- Adaptor
- Charger
- SMPS Standby Power



Package No to Scale

### Absolute Maximum Ratings

$T_C=25^\circ C$  unless otherwise specified

Symbol	Parameter	SK06N90B-TF	Unit
$V_{DSS}$	Drain-to-Source Voltage	900	V
$V_{GSS}$	Gate-to-Source Voltage	$\pm 30$	
$I_D$	Continuous Drain Current	6.0	A
$I_{DM}$	Pulsed Drain Current at $V_{GS}=10V$	24	
$E_{AS}$	Single Pulse Avalanche Energy	700	mJ
$P_D$	Power Dissipation	45	W
	Derating Factor above $25^\circ C$	0.29	$W/^\circ C$
$T_L$	Soldering Temperature Distance of 1.6mm from case for 10 seconds	300	$^\circ C$
$T_J & T_{STG}$	Operating and Storage Temperature Range	-55 to 150	

Caution: Stresses greater than those listed in the "Absolute Maximum Ratings" may cause permanent damage to the device.

### Thermal Characteristics

Symbol	Parameter	SK06N90B-TF	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	2.78	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	100	

## Electrical Characteristics

### OFF Characteristics

$T_J = 25^\circ\text{C}$  unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
$\text{BV}_{\text{DSS}}$	Drain-to-Source Breakdown Voltage	900	--	--	V	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$
$I_{\text{DSS}}$	Drain-to-Source Leakage Current	--	--	1	uA	$V_{\text{DS}}=900\text{V}, V_{\text{GS}}=0\text{V}$
		--	--	100		$V_{\text{DS}}=720\text{V}, V_{\text{GS}}=0\text{V}, T_J = 125^\circ\text{C}$
$I_{\text{GSS}}$	Gate-to-Source Leakage Current	--	--	+100	nA	$V_{\text{GS}}=+30\text{V}, V_{\text{DS}}=0\text{V}$
		--	--	-100		$V_{\text{GS}}=-30\text{V}, V_{\text{DS}}=0\text{V}$

### ON Characteristics

$T_J = 25^\circ\text{C}$  unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
$R_{\text{DS(ON)}}$	Static Drain-to-Source On-Resistance	--	1.4	1.9	$\Omega$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=3\text{A}$
$V_{\text{GS(TH)}}$	Gate Threshold Voltage	3.0	--	5.0	V	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$
$g_{\text{fs}}$	Forward Transconductance	--	8.0	--	S	$V_{\text{DS}}=15\text{V}, I_{\text{D}}=3\text{A}$

### Dynamic Characteristics

Essentially independent of operating temperature

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
$C_{\text{iss}}$	Input Capacitance	--	1460	--	pF	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=25\text{V}, f=1.0\text{MHz}$
$C_{\text{rss}}$	Reverse Transfer Capacitance	--	23	--		
$C_{\text{oss}}$	Output Capacitance	--	130	--		
$Q_g$	Total Gate Charge	--	37	--	nC	$V_{\text{DD}}=450\text{V}, I_{\text{D}}=6\text{A}, V_{\text{GS}}=0 \text{ to } 10\text{V}$
$Q_{\text{gs}}$	Gate-to-Source Charge	--	8.0	--		
$Q_{\text{gd}}$	Gate-to-Drain (Miller) Charge	--	14	--		

### Resistive Switching Characteristics

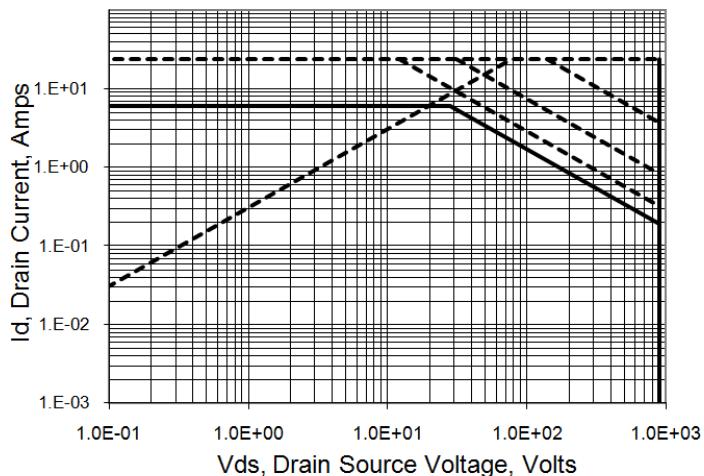
Essentially independent of operating temperature

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
$t_{\text{d(ON)}}$	Turn-on Delay Time	--	22	--	nS	$V_{\text{DD}}=450\text{V}, I_{\text{D}}=6\text{A}, V_{\text{GS}}=10\text{V}, R_g=9.1\Omega$
$t_{\text{rise}}$	Rise Time	--	45	--		
$t_{\text{d(OFF)}}$	Turn-Off Delay Time	--	33	--		
$t_{\text{fall}}$	Fall Time	--	37	--		

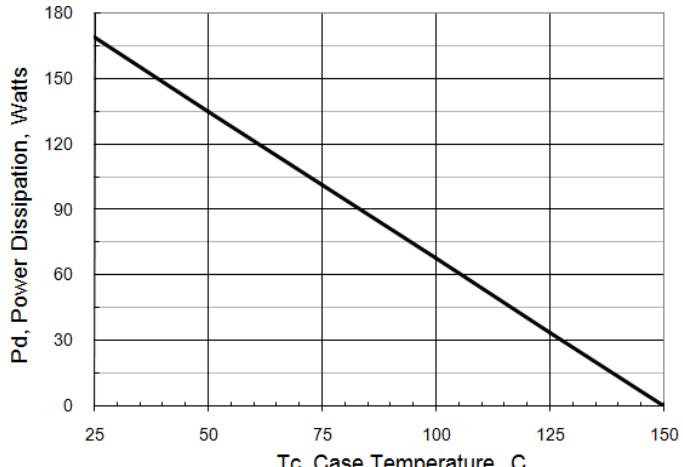
**Source-Drain Body Diode Characteristics**
 $T_J=25^\circ\text{C}$  unless otherwise specified

Symbol	Parameter	Min	Typ.	Max.	Unit	Test Conditions
$I_{SD}$	Continuous Source Current <sup>[2]</sup>	--	--	6	A	Integral pn-diode in MOSFET
$I_{SM}$	Pulsed Source Current <sup>[2]</sup>	--	--	24		
$V_{SD}$	Diode Forward Voltage	--	--	1.5	V	$I_S=6\text{A}$ , $V_{GS}=0\text{V}$
$t_{rr}$	Reverse Recovery Time	--	390	--	ns	$V_{GS}=0\text{V}$ $I_F= I_S$ , $di/dt=100\text{A}/\mu\text{s}$
$Q_{rr}$	Reverse Recovery Charge	--	1.4	--	uC	

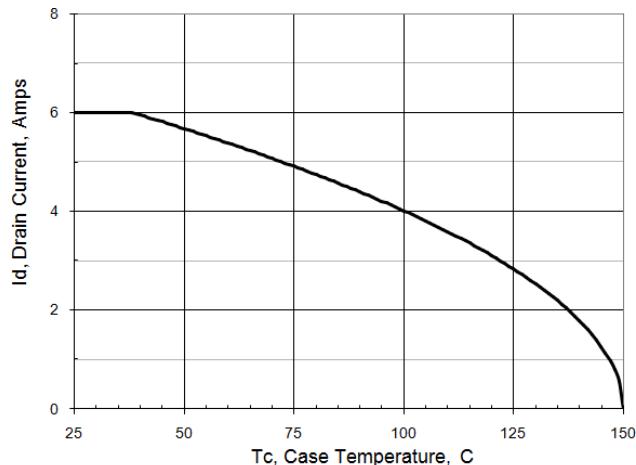
## Typical Characteristics



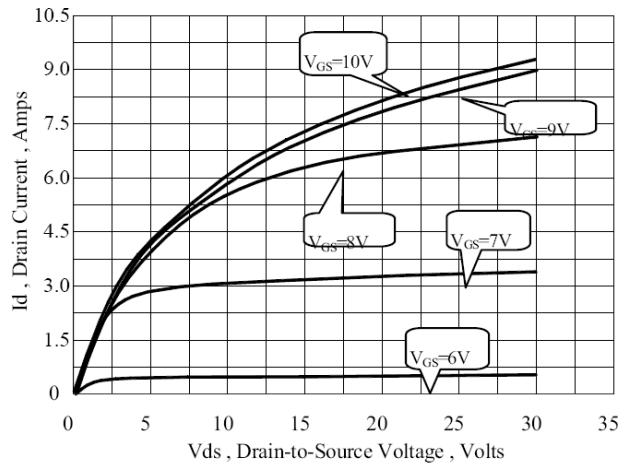
**Figure 1 . Maximum Safe Operating Area**



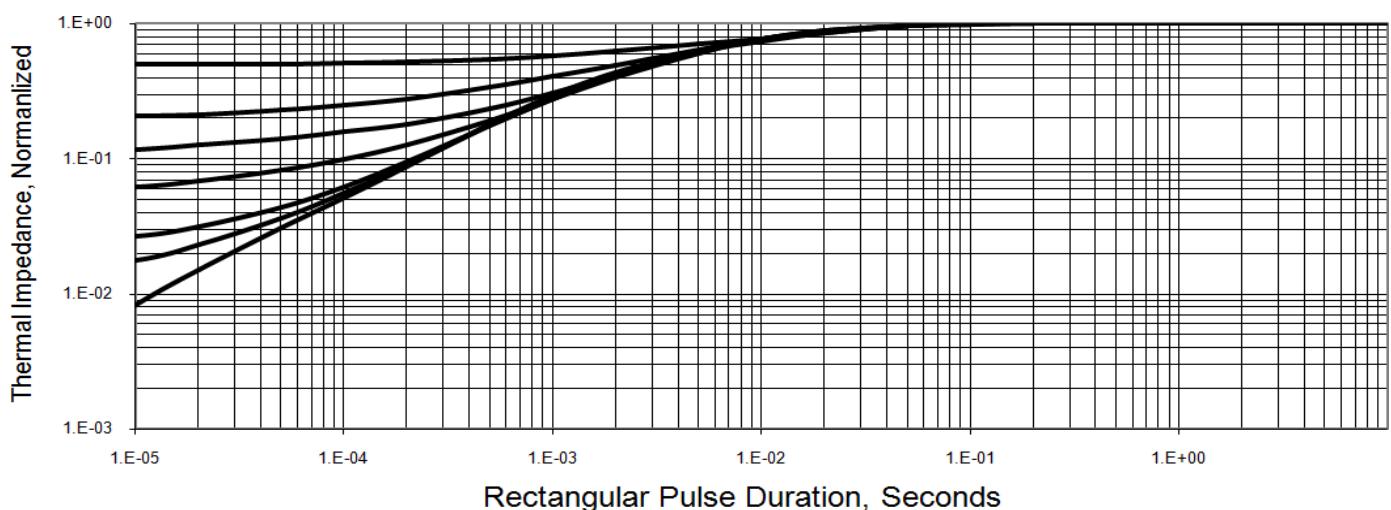
**Figure 2 . Maximum Power Dissipation vs Case Temperature**



**Figure 3 .Maximum Continuous Drain Current vs Case Temperature**

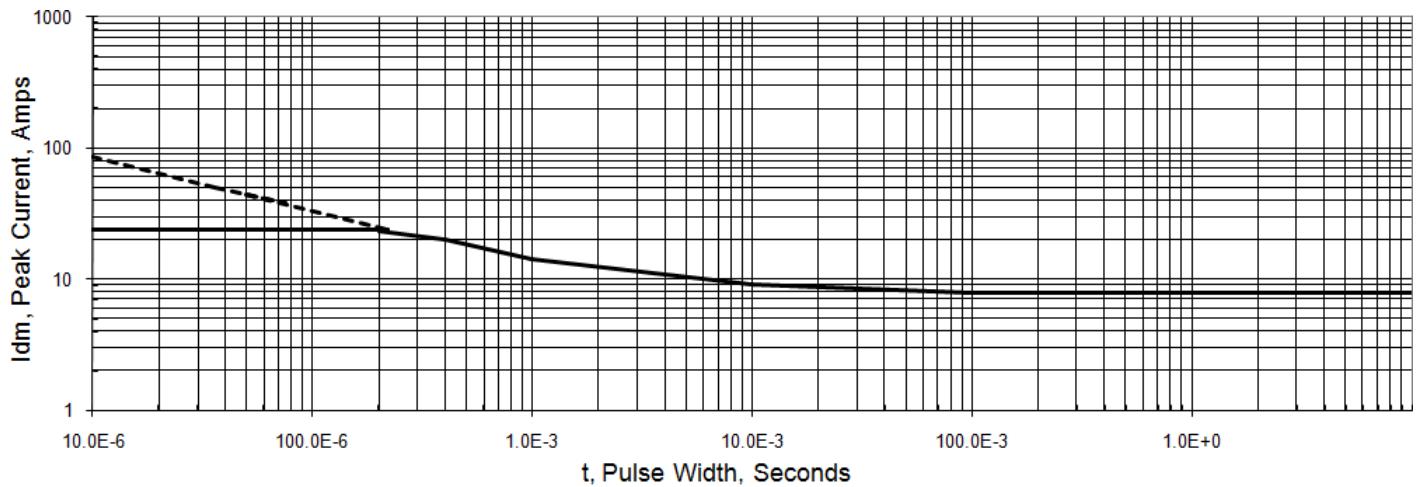


**Figure 4 Typical Output Characteristics**

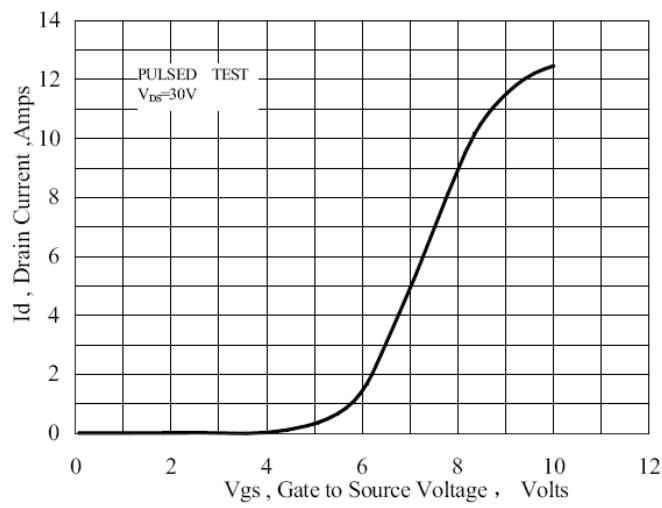


**Figure 5. Maximum Transient Thermal Impedance**

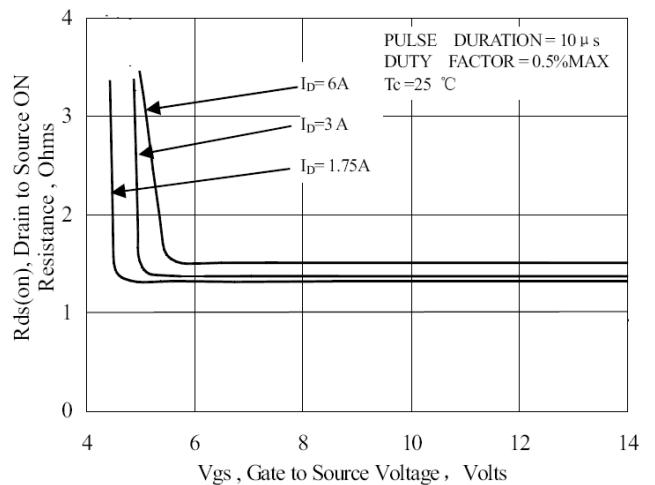
## Typical Characteristics(Cont.)



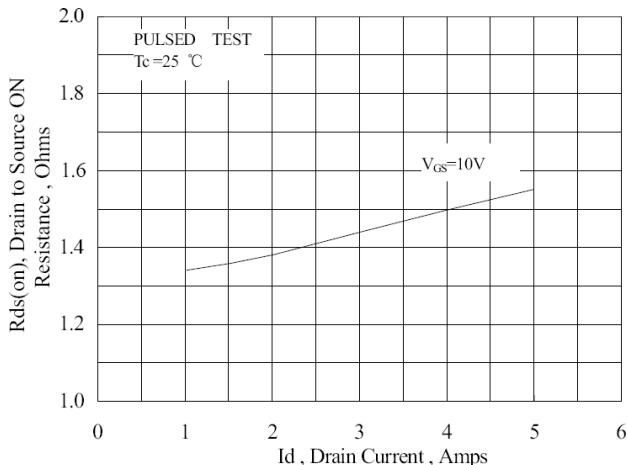
**Figure 6. Peak Current Capability**



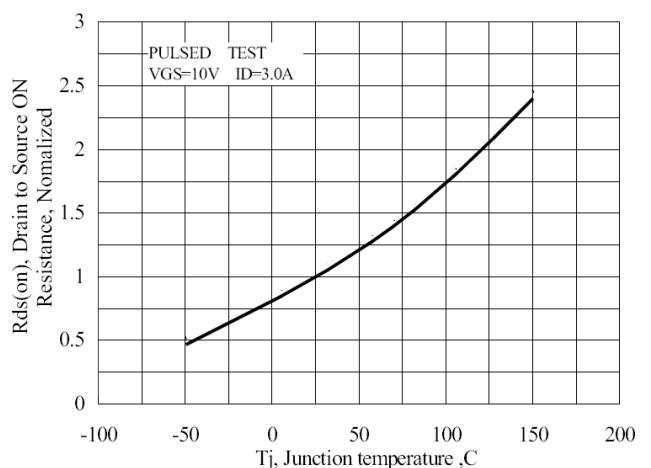
**Figure 7** Typical Transfer Characteristics



**Figure 8** Typical Drain to Source ON Resistance vs Gate Voltage and Drain Current



**Figure 9** Typical Drain to Source ON Resistance vs Drain Current



**Figure 10** Typical Drian to Source on Resistance vs Junction Temperature

## Typical Characteristics(Cont.)

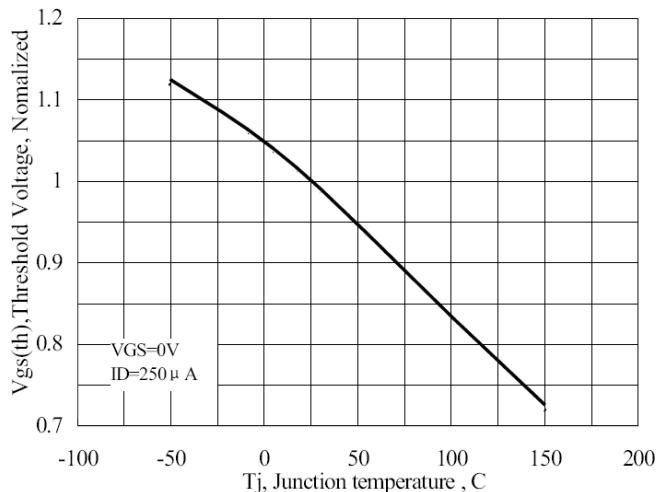


Figure 11 Typical Threshold Voltage vs Junction Temperature

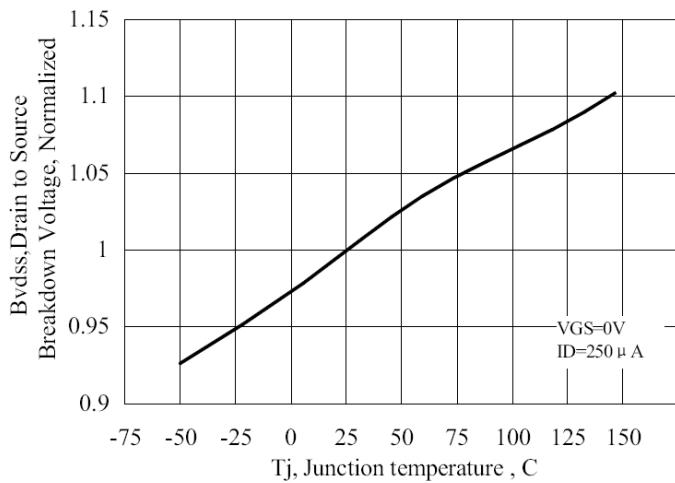


Figure 12 Typical Breakdown Voltage vs Junction Temperature

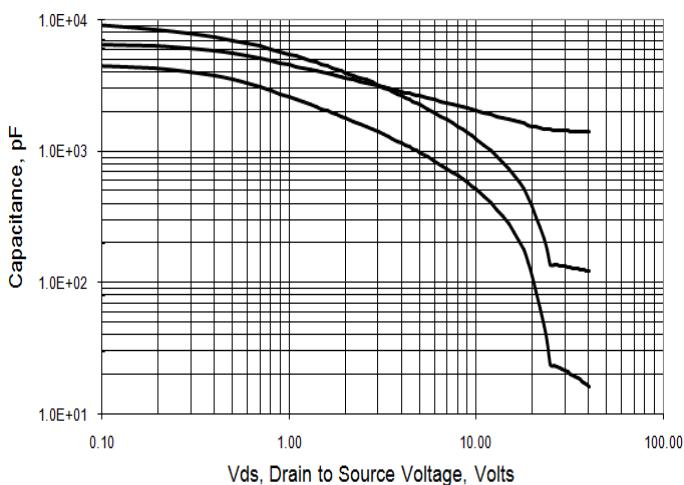


Figure 13. Capacitance vs Vds

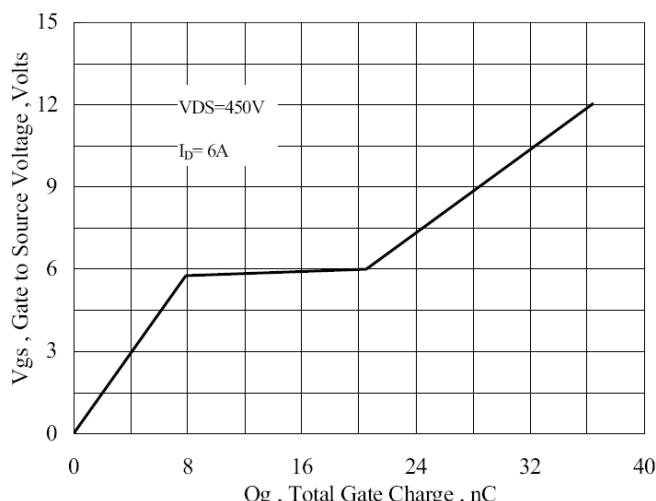


Figure 14 Typical Gate Charge vs Gate to Source Voltage

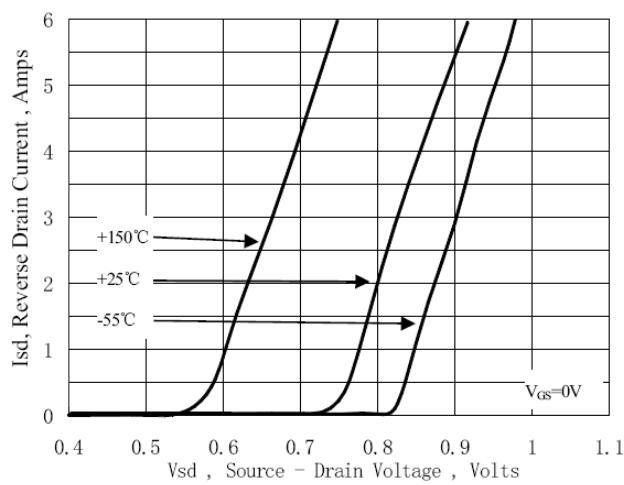


Figure 15 Typical Body Diode Transfer Characteristics

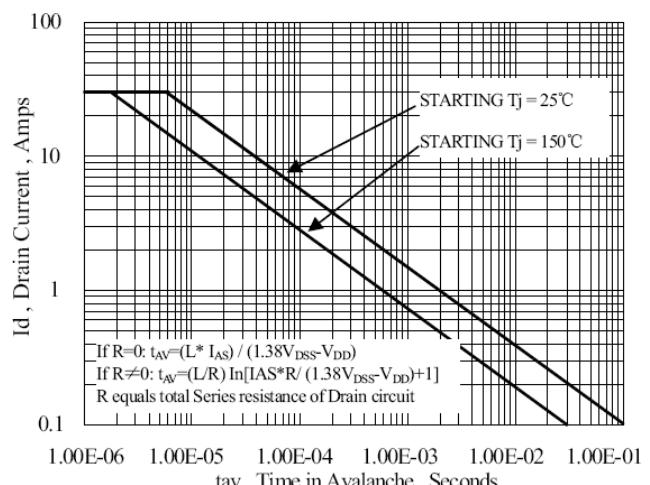


Figure 16 Unclamped Inductive Switching Capability

## Test Circuits and Waveforms

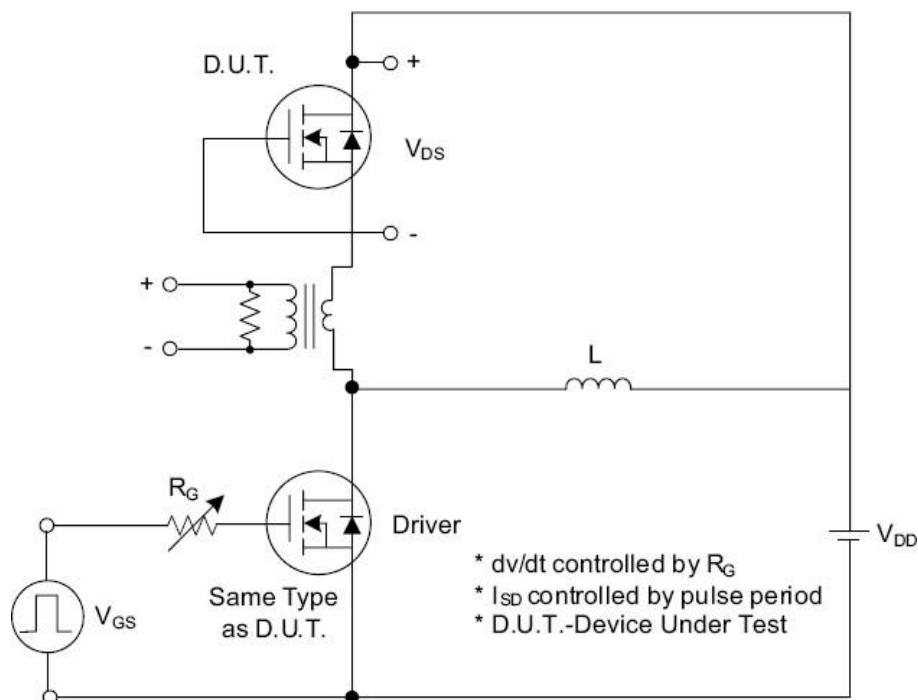


Fig. 1.1 Peak Diode Recovery dv/dt Test Circuit

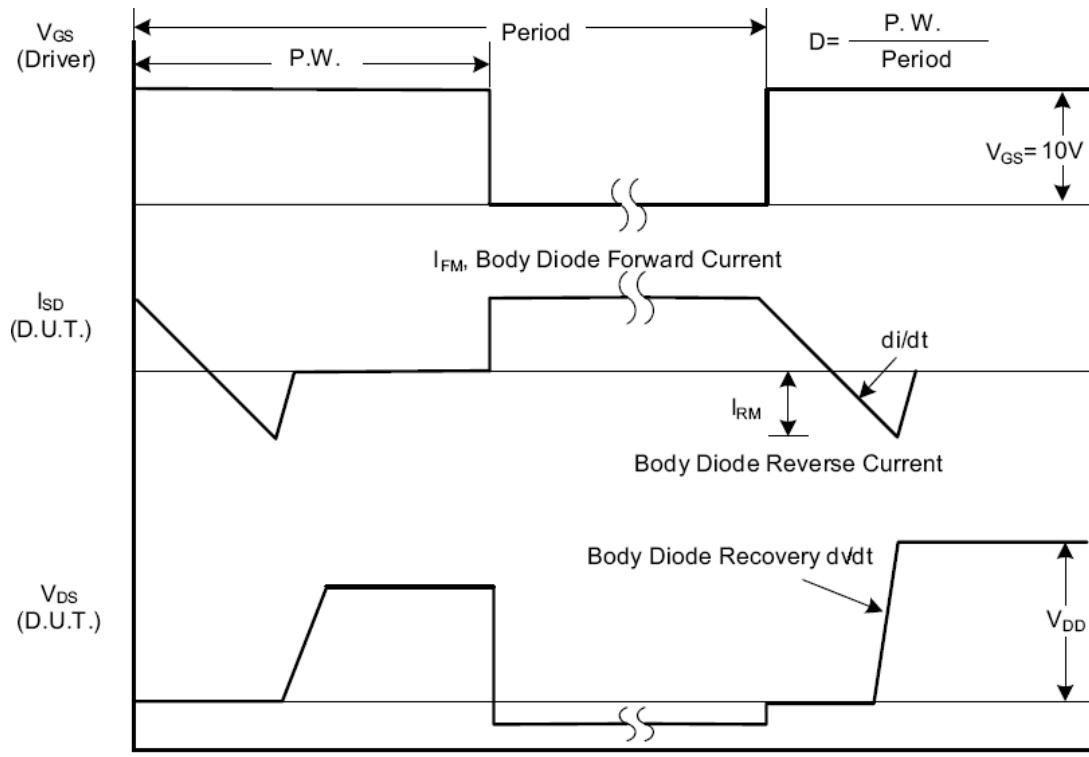


Fig. 1.2 Peak Diode Recovery dv/dt Waveforms

## Test Circuits and Waveforms (Cont.)

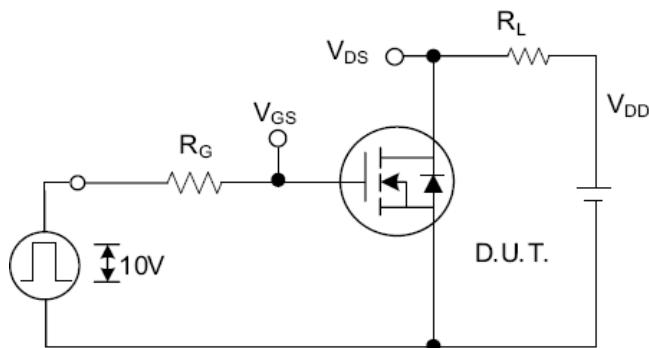


Fig. 2.1 Switching Test Circuit

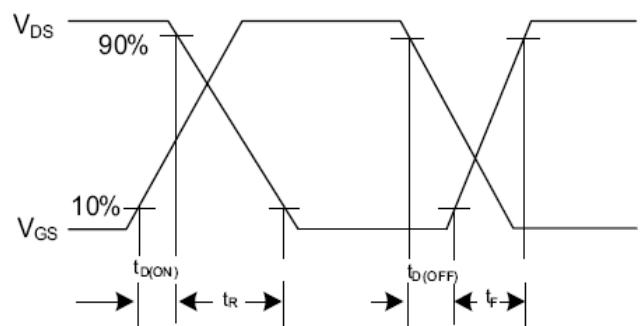


Fig. 2.2 Switching Waveforms

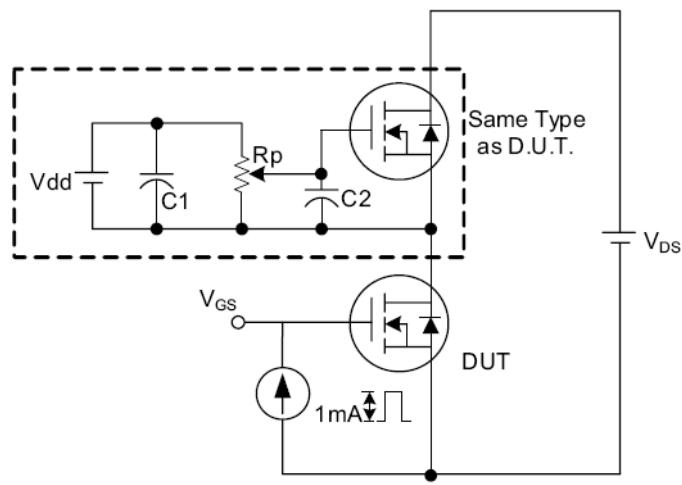


Fig. 3 . 1 Gate Charge Test Circuit

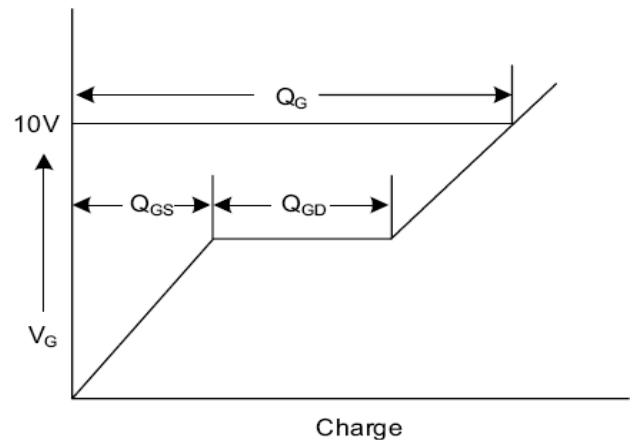


Fig. 3 . 2 Gate Charge Waveform

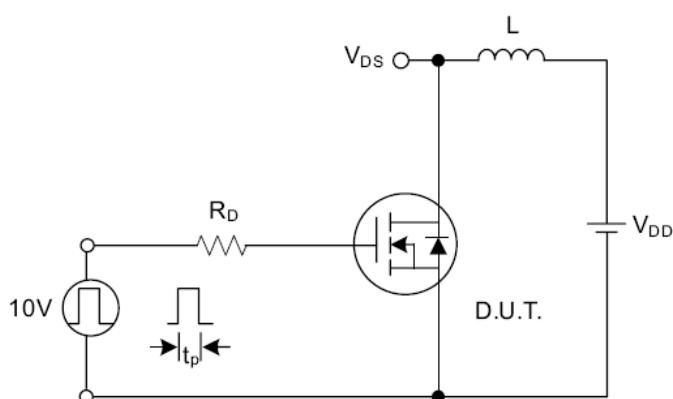


Fig. 4.1 Unclamped Inductive Switching Test Circuit

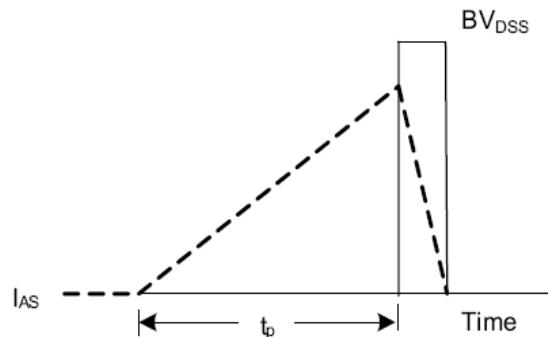


Fig. 4.2 Unclamped Inductive Switching Waveforms

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